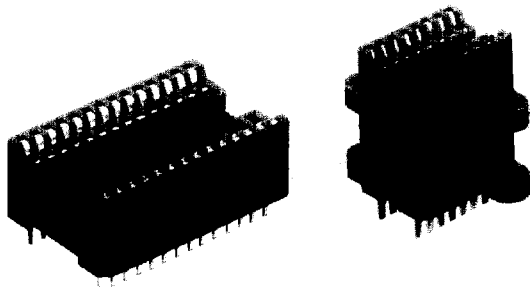


DIP(2.54mm pitch)



FEATURES

- Dual wipe contact ensures high reliability.
- A piggy-back design allows replacement of the top socket without desoldering.
- Two types of terminals available (solder dip and wire wrap).

SPECIFICATIONS

PERFORMANCE

Insulation Resistance	1,000M Ω min. at 500VDC
Dielectric Withstanding Voltage	700VAC rms for 1 minute
Contact Resistance	20m Ω max. at 10mA
Current Rating	1A
Operating Temperature Range	-55°C to +170°C

MATERIAL AND FINISH

Housing	PES (glass-filled), UL94V-0 rated
Contacts	Copper alloy, gold plating over nickel

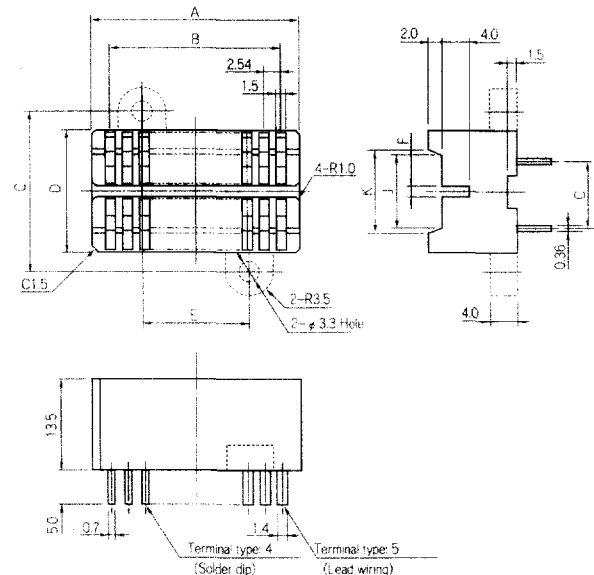
ORDERING CODE

IC114-1403-G4MF

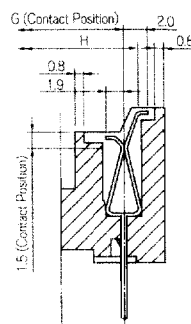
MF	Flange option	MF = With Unmarked = Without
	Straight solder dip terminal	
	Type of contact plating	G = Gold
	Distance between IC terminal rows:	03 = 0.3 inches
	Number of leads	

IC114 series

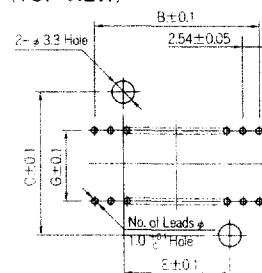
●Outline Dimensions



●Detail of Contact



●Recommended PC Board
Patterns
(TOP VIEW)



Part No.	No. of Leads	A	B	C	D	E	F	G	H	J	K
IC114-1403-G* (MF)	14	19.0	15.24	21.0	15.0	7.62	2.0	8.50	10.50	7.80	9.40
IC114-1603-G* (MF)	16	21.5	17.78	21.0	15.0	12.00	2.0	8.50	10.50	7.80	9.40
IC114-1803-G* (MF)	18	24.0	20.32	21.0	15.0	12.00	2.0	8.50	10.50	7.80	9.40
IC114-2003-G* (MF)	20	27.5	22.86	21.0	15.0	12.70	2.0	8.50	10.50	7.80	9.40
IC114-2204-G* (MF)	22	31.0	25.40	24.0	18.0	16.00	2.0	11.50	13.50	10.80	12.40
IC114-2404-G* (MF)	24	32.0	27.94	24.0	18.0	19.00	2.0	11.10	13.00	10.80	12.40
IC114-2804-G* (MF)	28	37.5	33.02	25.0	18.0	25.00	3.0	11.10	13.00	11.36	12.40
IC114-2806-G* (MF)	28	37.5	33.02	29.0	23.5	25.00	6.0	16.54	18.54	16.54	18.14
IC114-4006-G* (MF)	40	52.0	48.26	29.0	23.5	40.00	6.0	16.54	18.54	16.54	18.14
IC114-4206-G* (MF)	42	55.0	50.80	29.0	23.5	43.00	6.0	16.54	18.54	16.54	18.14
IC114-6409-G* (MF)	64	83.0	78.74	38.2	32.0	52.00	15.6	23.00	25.00	23.40	25.40

Unit = mm